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IEC 62899-202

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# INTERNATIONAL STANDARD

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**Printed electronics –  
Part 202: Materials – Conductive ink**

INTERNATIONAL  
ELECTROTECHNICAL  
COMMISSION

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# INTERNATIONAL ELECTROTECHNICAL COMMISSION

## PRINTED ELECTRONICS –

### Part 202: Materials – Conductive ink

#### FOREWORD

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International Standard IEC 62899-2-1 has been prepared by IEC technical committee 119: Printed electronics.

The text of this standard is based on the following documents:

FDIS	Report on voting
119/88/FDIS	119/101A/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62899 series, published under the general title *Printed electronics*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

## INTRODUCTION

The IEC 62899-20x series relates mainly to evaluation methods for materials of printed electronics. The series also include storage methods, packaging and marking, and transportation conditions.

The IEC 62899-20x series is divided into parts for each material. Each part is prepared as a generic specification containing fundamental information for the area of printed electronics.

The IEC 62899-20x series consists of the following parts:

Part 201: Materials – Substrates

Part 202: Materials – Conductive ink

Part 203: Materials – Semiconductor ink<sup>1</sup>

(Subsequent parts will be prepared for other materials.)

Furthermore, sectional specifications, blank detail specifications, and detail specifications of each material will follow these parts.

This part of IEC 62899 is prepared for conductive materials used in printed electronics and contains the test conditions, the evaluation methods and the storage conditions.

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<sup>1</sup> Under consideration.

## PRINTED ELECTRONICS –

### Part 202: Materials – Conductive ink

#### 1 Scope

This part of IEC 62899 defines the terms and specifies the standard methods for characterisation and evaluation.

This International Standard is applicable to conductive inks and conductive layer that are made from conductive inks.

#### 2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

ISO 5-2, *Photography and graphic technology – Density measurements – Part 2: Geometric conditions for transmittance density*

ISO 5-3, *Photography and graphic technology – Density measurements – Part 3: Spectral conditions*

ISO 124, *Latex, rubber – Determination of total solids content*

ISO 291, *Plastics – Standard atmospheres for conditioning and testing*

ISO 304, *Surface active agents – Determination of surface tension by drawing up liquid films*

ISO 489:1999, *Plastics – Determination of refractive index*

ISO 758, *Liquid chemical products for industrial use – Determination of density at 20 degrees C*

ISO 1183-1, *Plastics – Methods for determining the density of non-cellular plastics – Part 1: Immersion method, liquid pycnometer method and titration method*

ISO 2555, *Plastics – Resins in the liquid state or as emulsions or dispersions – Determination of apparent viscosity by the Brookfield Test method*

ISO 2592, *Determination of flash and fire points – Cleveland open cup method*

ISO 2719, *Determination of flash point – Pensky-Martens closed cup method*

ISO 2811-1, *Paints and varnishes – Determination of density – Part 1: Pycnometer method*

ISO 2811-2, *Paints and varnishes – Determination of density – Part 2: Immersed body (plummet) method*

ISO 2884-1, *Paints and varnishes – Determination of viscosity using rotary viscometers – Part 1: Cone-and-plate viscometer operated at a high rate of shear*

ISO 3219, *Plastics – Polymers/resins in the liquid state or as emulsions or dispersions – Determination of viscosity using a rotational viscometer with defined shear rate*

ISO 3451-1, *Plastics – Determination of ash – Part 1: General methods*

ISO 3664, *Graphic technology and photography – Viewing conditions*

ISO 3679, *Determination of flash no-flash and flash point – Rapid equilibrium closed cup method*

ISO 4576, *Plastics – Polymer dispersions – Determination of sieve residue (gross particle and coagulum content)*

ISO 9276-6, *Representation of results of particle size analysis – Part 6: Descriptive and quantitative representation of particle shape and morphology*

ISO 13319, *Determination of particle size distributions – Electrical sensing zone method*

ISO 13320, *Particle size analysis – Laser diffraction methods*

ISO 13321, *Particle size analysis – Photon correlation spectroscopy*

ISO 13322-1, *Particle size analysis – Image analysis methods – Part 1: Static image analysis methods*

ISO 13468-1:1996, *Plastics – Determination of the total luminous transmittance of transparent materials – Part 1: Single beam instrument*

ISO 13468-2:1999, *Plastics – Determination of the total luminous transmittance of transparent materials – Part 2: Double-beam instrument*

ISO 13655, *Graphic technology – Spectral measurement and colorimetric computation for graphic arts images*

ISO 14488, *Particulate materials – Sampling and sample splitting for the determination of particulate properties*

ISO 14782, *Plastics – Determination of haze for transparent materials*

ISO 14887, *Sample preparation – Dispersing procedures for powders in liquids*

ISO 20998-1, *Measurement and characterization of particles by acoustic methods – Part 1: Concepts and procedures in ultrasonic attenuation spectroscopy*